5x7mm Precision TCXO In Stock at Digi-Key



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Description:

The Connor-Winfield's DV75D is a 5x7mm Surface Mount Temperature Compensated Crystal Controlled Oscillator (TCXO) with LVCMOS output. Through the use of Analog Temperature Compensation, the DV75D is capable of holding sub 1-ppm stabilities over the -40 to 85°C temperature range.

Applications:

GR-253-CORE (SMC) ITU-T-G.813 Option 1 and 2 (SEC)



Features:

Model: DV75D

TCXO 3.3 Vdc Operation LVCMOS Output

Frequency Stability: ± 1.0 ppm
Temperature Range: -40 to 85°C
Low Jitter <1ps RMS

Tape and Reel Packaging
RoHS Compliant / Pb Free RoHS

Absolute Maximum Ratings

Parameter	Minimum	Nominal	Maximum	Units	Notes
Storage Temperature	-55	-	85	°C	
Supply Voltage (Vcc)	-0.5	-	6.0	Vdc	
Input Voltage	-0.5	-	Vcc+0.5	Vdc	

Operating Specifications

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Parameter	Minimum	Nominal	Maximum	Units	Notes
Nominal Frequency (Fo)	-	10.0, 12.8 or 20.0	-	MHz	
Frequency Calibration @ 25 °C	-1.0	-	1.0	ppm	1
Frequency Stability vs. Temperature	-1.0	-	1.0	ppm	2
Frequency vs. Load Stability	-0.2	-	0.2	ppm	±5%
Frequency vs. Voltage Stability	-0.2	-	0.2	ppm	±5%
Static Temperature Hysteresis	-	-	0.4	ppm	3
Aging	-1.0	-	1.0	ppm/year	
Operating Temperature Range:	-40	-	85	°C	
Supply Voltage (Vcc)	3.135	3.3	3.465	Vdc	±5%
Supply Current (Icc)	-	-	6	mA	
Period Jitter	-	3	5	ps rms	
Integrated Phase Jitter	-	0.5	1.0	ps rms	4
Typical Phase Noise Fo = 20.0 MHz					
SSB Phase Noise at 10Hz offset	-	-80	-	dBc/Hz	
SSB Phase Noise at 100Hz offset	-	-110	-	dBc/Hz	
SSB Phase Noise at 1KHz offset	-	-135	-	dBc/Hz	
SSB Phase Noise at 10KHz offset	-	-150	-	dBc/Hz	
SSB Phase Noise at 100KHz offset	t -	-150	-	dBc/Hz	
Start-up Time	-	-	10	ms	

LVCMOS Output Characteristics

Parameter	Minimum	Nominal	Maximum	Units	Notes
Load	-	15	-	рF	5
Voltage (High) (Voh)	90%Vcc	-	-	Vdc	
(Low) (Vol)	-	-	10%Vcc	Vdc	
Duty Cycle at 50% of Vcc	45	50	55	%	
Rise / Fall Time 10% to 90%	-	-	8	ns	

Package Characteristics

Package Herme	tically sealed crysta	al mounted on a c	ceramic package
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Environmental Characteristics

Vibration:	Vibration per Mil Std 883	BE Method 2007.3 Test Condition A
Shock:	Mechanical Shock per M	1il Std 883E Method 2002.4 Test Condition B.
Soldering Pro	cess; RoHS compliant lead fre	e. See soldering profile on page 2.

Ordering Information DV75D-010.0M*, DV75D-012.8M* or DV75D-020.0M*

* For the tape and reel option, add -T to the end of the part number. Example: DV75D-010.0M-T

Notes:

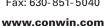
- 1. Initial calibration @ 25°C. Specifications at time of shipment after 48 hours of operation.
- 2. Frequency stability vs. change in temperature. $[\pm(Fmax Fmin)/(2*Fo)]$.
- 3. Frequency change after reciprocal temperature ramped over the operating range. Frequency measured before and after at 25°C.

 4. BW = 12 KHz to 20 MHz.
- 5. For best performance it is recommended that the circuit connected to this output should have an equivalent input capacitance of 15pF.

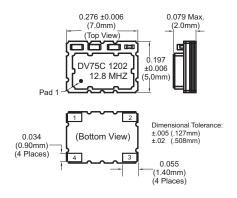


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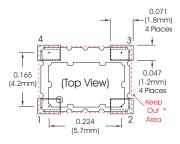
Phone: 630-851-4722 Fax: 630-851-5040



Package Layout



Suggested Pad Layout

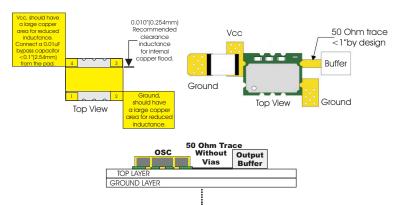


* Do not route any traces in the keep out area. It is recommended the next layer under the keep out area is to be ground plane.

Pad Connections

1:	N/C
2:	Ground
3:	Output (Fo)
4:	Supply Voltage (Vcc)

Design Recommendations



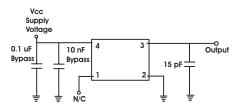
Attention: To achieve optimal frequency stability, and in some cases to meet the specification stated on this data sheet, it is required that the circuit connected to this TCXO output must have the equivalent input capacitance that is specified by the nominal load capacitance. Deviations from the nominal load capacitance will have a graduated effect on the stability of approximately 20 ppb per pF load difference.

BOTTOM LAYER

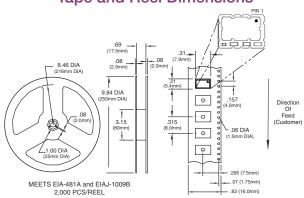
Output Waveform



Test Circuit



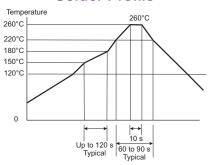
Tape and Reel Dimensions



Revision History

Revision 00	Data sheet released 01/11/12
Revision 01	Removed tri-state information from features and description. 11/26/12.
Revision 02	Added "Applications" 04/15/13

Solder Profile



Meets IPC/JEDEC J-STD-020C

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